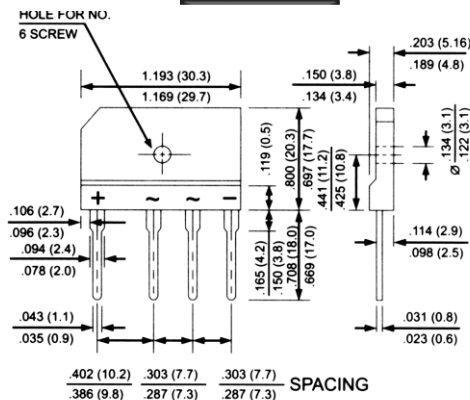


Features

- ◆ Rating to 1000V PRV
- ◆ Ideal for printed circuit boards
- ◆ Low forward voltage drop, high current capability
- ◆ Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- ◆ The plastic material has Underwriters Laboratory Flammability Classification 94V-0



Maximum Ratings and Electrical Characteristics

Dimensions in inches and (millimeters)

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Parameter	Symbols	KBJ8A	KBJ8B	KBJ8D	KBJ8G	KBJ8J	KBJ8K	KBJ8M	Units
		GBJ8A	GBJ8B	GBJ8D	GBJ8G	GBJ8J	GBJ8K	GBJ8M	
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	Volts
Maximum average forward rectified output current @ $T_c=100^\circ\text{C}$ (with heatsink Note 2) (without heatsink)	$I_{F(AV)}$					8.0 2.9			Amps
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}					170.0			Amps
Max. instantaneous forward voltage drop at 4.0A DC	V_F					1.0			Volt
Maximum DC reverse current @ $T_j=25^\circ\text{C}$ at rated DC blocking voltage per element @ $T_j=125^\circ\text{C}$	I_R					5.0 500.0			μA
Rating for fusing (t<8.3ms)	I_t					120			A^2sec
Typical junction capacitance per element (Note 1)	C_j					55			pF
Typical thermal resistance (Note 2)	$R_{\theta JC}$					1.6			$^\circ\text{C}/\text{W}$
Operating temperature range	T_j					-55 to +150			$^\circ\text{C}$
Storage temperature range	T_{STG}					-55 to +150			$^\circ\text{C}$

- Notes:**
1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC
 2. Device mounted on 100mm x 100mm x 1.6mm Cu plate heatsink

RATINGS AND CHARACTERISTIC CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

